

Amendments to the Specification:

Please replace the paragraph on page 3, line 24, to page 4, line 6, of the application as filed with the following amended paragraph:

Due to the forgoing problems, it goes without saying that it is necessary to reduce conventional impurities such as transition metal, high melting point metal, alkali metal, alkaline earth metal or other metals. Nevertheless, the aforementioned particles are formed even when decreasing the elements thereof as much as possible, and the current status is that the fundamental solution for such problems is yet to be discovered.

Please replace the paragraph on page 4, line 22, to page 5, line 11, of the application as filed with the following amended paragraph:

The present invention provides 1) a titanium target for sputtering wherein the oxygen contained in the titanium target for sputtering is 20ppm or less and the average grain diameter of such target is $20\mu\text{m}$ or less; 2) a titanium target for sputtering wherein the impurity concentration of gas components such as oxygen, nitrogen and hydrogen contained in the titanium target is 20ppm or less; 3) a titanium target for sputtering according to 1) or 2) above, wherein the Vickers hardness (Vs) is 120 or less; and 4) a titanium target for sputtering according to any one of 1) to 3) above, wherein the total content of alkali metal and alkaline earth metal such as Na and K is 5ppm or less, the total content of heavy metal and light metal is 10ppm or less, and the total content of radioactive elements such as U and Th of 1ppb or less.